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ABSTRACT OF THE DISCLOSURE

A system and method of coinsurance wafer management. The system includes at least one production line and an order management unit. The production line processes a MPW shuttle including original wafers and coinsurance wafers with a common fabrication process before metal layering, processes the original wafers with different metal layering fabrication processes according to a metal layering technology of each device design of the MPW shuttle, and withholds the coinsurance wafers without further fabrication. The order management unit receives a request for a designated device design before a cutoff date, and the production line releases and processes coinsurance wafers with the metal layering fabrication process corresponding to the designated device design when the request is received.